EAST search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S5	86	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) near10 (wiring near board or substrate or interposer or circuit adj board or pcb or pwb or carrier) and (imager or camera or ccd) near6 (visual or view or vision) near (field) near10 (location or position or inspecting or inspection or detection or detecting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:00
S6	2	("5814894" | "6113728").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/31 09:04
S7	14	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near6 (visual or view or vision or viewing or imaging) near (field or area or region) near5 ("next" or "adjacent" or neighboring or neighbor or prior or previous or surrounding or nearby)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:50
S9	6	("5946409").URPN.	USPAT	OR	ON	2005/08/31 10:08
S8	52	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near6 (visual or view or vision or viewing or imaging) near (field or area or region) near5 (plural or plurality or multiple or two or three or several)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 10:14
S11	193	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near (single)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 10:16
S13	488	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera) near6 (visual or view or vision) near (field)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 12:48
S14	227	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near6 (visual or view or vision) near (field) near10 (location or position or inspecting or inspection or detection or detecting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:30
S12	101	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near3 (inspection or inspecting or inspect or testing or test or examination or examining or check or checking or monitor or monitoring) near3 (mounted or post or after or attached or bonded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:00
S15	10	(chip or die or ic or integrated adj circuit or semiconductor near device) near6 (bonding or bond or attachment or attach or attaching or mount or mounting or mounted or affixing or adhering) and (dual or split or double) near3 (field or view) near4 (camera or imager or ccd)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:23
S16	959	(chip or die or ic or integrated adj circuit or semiconductor near device) near6 (bonding or bond or attachment or attach or attaching or mount or mounting or mounted or affixing or adhering) and (plural or plurality or multiple or multi or two or "next" or adjacent or neighbor or neighboring) near3 (chip or die or ic or circuit or device) near6 (camera or ccd or imager or imaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:25
S17	217	(chip or die or ic or integrated adj circuit or semiconductor near device) near6 (bonding or bond or bonder or attacher or mounter or attachment or attach or attaching or mount or mounting or mounted or affixing or adhering) same (plural or plurality or multiple or multi or two or "next" or adjacent or neighbor or neighboring) near3 (chip or die or ic or circuit or device) near6 (camera or ccd or imager or imaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:26

S1	1969	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera) near6 (position or inspection or inspecting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 13:14
S18	192	(die or chip or ic or integrated adj circuit or semiconductor near device or solid near device) near3 (bonding or bond or bonded or bonder or attachment or attaching or attach or mounting or mounted or mounter or affixing or sealing or joining or joiner or attached) near15 (imager or camera or ccd) near4 (inspection or inspecting or inspected or monitor or monitoring or detector or detected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 15:45
S19	75	(die or chip or ic or integrated adj circuit or semiconductor near device or solid near device) near3 (bonding or bond or bonded or bonder or attachment or attaching or attach or mounting or mounted or mounter or affixing or sealing or joining or joiner or attached) near15 (imager or camera or ccd or imaging) near4 (view or viewing or vision or imaging or image) near2 (area or region or field)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:44
S20	87	(die or chip or ic or integrated adj circuit or semiconductor near device or solid near device) near3 (bonding or bond or bonded or bonder or attachment or attaching or attach or mounting or mounted or mounter or affixing or sealing or joining or joiner or attached) and (imager or camera or ccd or imaging) near4 (inspection or inspecting or testing or test or sorting or sorted or inspected) near4 (chip or die or ic or integrated near circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:46
S22	399	438/107.cor.	US-PGPUB; USPAT	OR	ON	2005/09/22 12:21
S21	16	(US-20010051394-$ or US-20020008528-$ or US-20020019066-$ or US-20020102016-$ or US-20030189161-$ or US-20040148769-$ or US-20050088666-$ or US-20030088973-$).did. or (US-5547537-$ or US-5946408-$ or US-5946409-$ or US-6389688-$ or US-6839959-$ or US-5975835-$ or US-5878484-$ or US-5858806-$).did.	US-PGPUB; USPAT	OR	ON	2005/09/22 12:21
S23	79	438/107.cor. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT	OR	ON	2005/09/22 12:33
S25	87	438/108.cor. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT	OR	ON	2005/09/22 12:34
S24	467	438/108.cor.	US-PGPUB; USPAT	OR	ON	2005/09/22 12:47
S26	99	438/110.cor.	US-PGPUB; USPAT	OR	ON	2005/09/22 12:58
S27	98	438/111.cor.	US-PGPUB; USPAT	OR	ON	2005/09/22 13:08
S28	101	29/833.cor.	US-PGPUB; USPAT	OR	ON	2005/09/22 13:52
S29	92	29/834.cor.	US-PGPUB; USPAT	OR	ON	2005/09/26 13:19
L3	34	29/836.cor.	US-PGPUB; USPAT	OR	ON	2005/09/26 13:29
L4	261	382/149.cor.	US-PGPUB; USPAT	OR	ON	2005/09/26 14:10
L5	288	(chip or die or module or device or component or ic or circuit) near4 (attach$4 or mount$4 or bond$4 or packaging) same (ccd or camera) near4 (after or post)	US-PGPUB; USPAT	OR	ON	2005/09/26 14:13
L6	101	(chip or die or module or device or component or ic or circuit) near4 (attach$4 or mount$4 or bond$4 or packaging) same (ccd or camera) near4 (after or post) near4 (attach$4 or bond$4 or mount$4 or affixing or adhering or soldering or packaging)	US-PGPUB; USPAT	OR	ON	2005/09/26 14:24
L7	12	("4941256").URPN.	USPAT	OR	ON	2005/09/26 15:08

L9	57	(chip or die or ic or circuit or semiconductor near device or solid near2 device) near4 (package or packaging) near15 (ccd or camera) near6 (inspect$4 or monitor$4 or detect$4)	USPAT	OR	ON	2005/09/26 15:09
L8	187	(chip or die or ic or circuit or semiconductor near device or solid near2 device) near4 (package or packaging) near6 (ccd or camera)	USPAT	OR	ON	2005/09/26 15:09
S2	90	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera) near6 (inspection or inspecting or test or testing) near10 (position or positioning or location or locating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 15:20
L11	223	(die or chip or ic or integrated adj circuit) near3 (package or packaging) and (imager or camera or ccd) near6 (visual or view or viewing) near3 (area or region or field)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:44
L10	91	(die or chip or ic or integrated adj circuit) near3 (package or packaging) and (imager or camera) near6 (inspection or inspecting or test or testing) near10 (position or positioning or location or locating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:44
L12	96	(die or chip or ic or integrated adj circuit) near3 (package or packaging) and (chip or die or ic or integrated near circuit) near10 (imager or camera or ccd) near6 (visual or view or viewing) near3 (area or region or field)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:52
L13	2621	(die or chip or ic or integrated adj circuit) near3 (package or packaging or bond$4 or mount$4 or attach$4 or flip or affixing) and (plural or plurality or multiple or multi or several or line or second) near4 (chip or die or ic or integrated near circuit) near10 (simultaneous$2 or ("same" or identical or single) near2 (time or shot or frame) near6 (imager or camera or ccd or imaging or image or snapshot or picture or photo or video))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:56
L14	17	(die or chip or ic or integrated adj circuit) near3 (package or packaging or bond$4 or mount$4 or attach$4 or flip or affixing) and (plural or plurality or multiple or multi or several) near4 (chip or die or ic or integrated near circuit) near5 (simultaneous$2 or ("same" or identical or single) near2 (time or shot or frame)) near5 (imager or camera or ccd or imaging or image or snapshot or picture or photo or video)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 16:57

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Inspec Search notes

databases   easy search

Advanced Search: INSPEC - 1969 to date (INZZ)

limit

Search history:

No.	Database	Search term	Info added since	Results	
1	INZZ	(chip OR die OR ic OR circuit OR device) NEAR (bond$3 OR attach$4 OR affixing OR adhering OR package OR packaging) AND (ccd OR camera) NEAR (visual OR view OR imaging OR image) NEAR (field OR area OR region)	unrestricted	5	show titles
2	INZZ	(chip OR die OR ic OR circuit OR device) NEAR (bond$3 OR attach$4 OR affixing OR adhering OR package OR packaging) AND (ccd OR camera OR imager) NEAR (inspect$4 OR detect$4)	unrestricted	18	show titles
3	INZZ	(chip OR die OR ic OR circuit OR device) NEAR (bond$4 OR attach$4 OR affixing OR adhering OR package OR packaging) AND (post OR after) NEAR inspect$4	unrestricted	58	show titles
4	INZZ	(chip OR die OR ic OR circuit OR device) NEAR (bond$4 OR attach$4 OR affixing OR adhering OR mount$4 OR package OR packaging) AND (post OR after) NEAR inspect$4 NEAR (ccd OR camera OR imager)	unrestricted	1	show titles
6	INZZ	(chip OR die OR ic OR circuit OR device) NEAR (bond$4 OR attach$4 OR mount$4 OR affixing OR adhering OR package OR packaging) NEAR (apparatus OR machine OR robotic OR robot OR automated) AND (camera OR ccd)	unrestricted	18	show titles
7	INZZ	(chip OR die OR ic OR device OR circuit OR leadframe) AND (ccd OR camera) NEAR (vision OR visual OR view OR image) NEAR (field OR region OR area)	unrestricted	164	show titles
8	INZZ	(chip OR die OR ic OR device OR circuit OR leadframe) NEAR (detect$4 OR inspect$4 OR locat$4 OR position$4) AND (ccd OR camera) NEAR (vision OR visual OR view OR image) NEAR (field OR region OR area)	unrestricted	27	show titles

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Edit an existing query or compose a new query in the Search Query Display.

Search Query Display

Select a search number (#) to:
- Add a query to the Search Query Display
- Combine search queries using AND, OR, or NOT
- Delete a search
- Run a search

Recent Search Queries

#1 (((chip or die or circuit or ic) <near/4> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing) and (ccd or camera) <near/6> (inspection or inspecting or inspected))<in>metadata)

#2 (((chip or die or circuit or ic) <near/4> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing) and (ccd or camera) <near/6> (inspection or inspecting or inspected))<in>metadata)

#3 (((chip or die or circuit or ic) <near/4> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing) and (ccd or camera) <near/6> (view or viewing or imaging or image) <near/6> (area or region or field))<in>metadata)

#4 (((chip or die or circuit or ic) <near/2> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing) and (ccd or camera))<in>metadata)

#5 (((chip or die or circuit or ic) <near/2> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing or package or packaging) and (ccd or camera) <near/6> (fault or faulty or error or bad or post or after or finished or complete or completed) <near/6> (detecting or detector or detection or detected or inspection or inspected or monitored))<in>metadata)

#6 (((chip or die or circuit or ic) <near/2> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing or package or packaging) <near/3> (apparatus or machine))<in>metadata)

#7 (((((chip or die or circuit or ic) <near/2> (bonding or bond or attach or attachment or attaching or mounting or mounter or affixing or package or packaging) <near/3> (apparatus or machine))<in>metadata))<AND>((ccd or camera or imager or imaging)<in>metadata))

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